



Material Content Data Sheet



Sales Product Name		TLE4309G		Issued		1. August 2018		
MA#		MA000722704						
Package		PG-TO263-7-1		Weight*		1566.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.611	0.23	0.23	2305	2305
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		155	
	non noble metal	iron	7439-89-6	0.810	0.05		517	
	non noble metal	copper	7440-50-8	808.613	51.61	51.68	516108	516780
	non noble metal	aluminium	7429-90-5	0.180	0.01	0.01	115	115
wire	non noble metal	aluminium	7429-90-5	0.180	0.01	0.01	115	115
encapsulation	organic material	carbon black	1333-86-4	1.257	0.08		802	
	plastics	epoxy resin	-	57.831	3.69		36912	
	inorganic material	silicondioxide	60676-86-0	569.510	36.35	40.12	363498	401212
leadfinish	non noble metal	tin	7440-31-5	13.037	0.83	0.83	8321	8321
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	136	137
solder	non noble metal	tin	7440-31-5	0.102	0.01		65	
	noble metal	silver	7440-22-4	0.127	0.01		81	
	non noble metal	lead	7439-92-1	4.867	0.31	0.33	3106	3252
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		20	
	non noble metal	iron	7439-89-6	0.106	0.01		68	
	non noble metal	copper	7440-50-8	106.210	6.78	6.79	67790	67878
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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